



# APPROVAL SHEET

Issued No. :

**DESCRIPTION** : SMD 5032 CRYSTAL  
**NOMINAL FREQ.** : 8.00 MHz  
**TAITIEN P/N** : \_\_\_\_\_  
**TAITIEN MODEL** : 5032-8.00-8-10-102PB  
**REVISION** : 1  
**DATE** : 06/19/2017

QA	Checked	Prepared

**CUSTOMER** : \_\_\_\_\_

**CUSTOMER P/N** : \_\_\_\_\_

Customer Signature
Approved:
Date:





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## ELECTRICAL SPECIFICATIONS

	Parameter	Min.	Typ.	Max.	Units	Test Condition
1-1	Nominal Frequency	8.00			MHz	
1-2	Frequency Tolerance.	-10		+10	ppm	at 25°C +/-2°C
1-3	Operating Temperature range	-20		+75	°C	
1-4	Storage Temperature range	-40		+85	°C	
1-5	Temperature Characteristics	-10		+10	ppm	-30°C to +75°C
1-6	Nominal Load Capacitance	8			pF	
1-7	Series Resistance			100	Ω	
1-8	Shunt Capacitance			7	pF	
1-9	Motion Capacitance				fF	
1-10	Motion Inductance				mH	
1-11	Q factor				K	
1-12	Spurious Response				dB	
1-13	Frequency Pull ability				ppm/pF	
1-14	C0/C1 Ratio					
1-15	Aging	-3		+3	ppm/year	
1-16	Insulation Resistance	500MΩ Min. @ DC100V				
1-17	Nominal Drive Level	10			μW	into 10Ω
1-18	Dependency Condition				μW	
1-19	Drive Level Dependency Resistance Max. Minus Min.				Ω	
1-20	Drive Level Dependency Frequency Max. Minus Min.				ppm	
1-21	Drive Level Dependency Resistance Max.				Ω	



## ■ CUSTOMER SPECIAL REQUIREMENT

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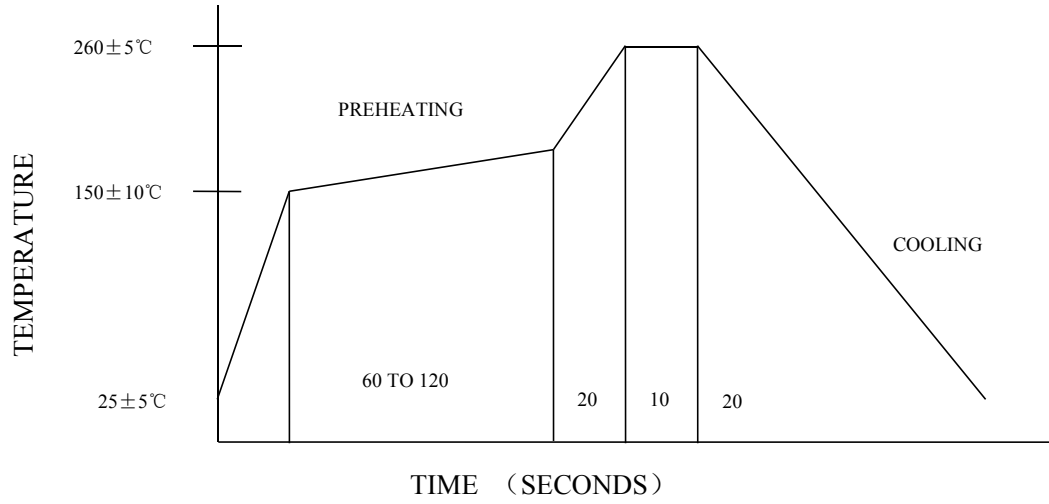
## ■ ENVIRONMENTAL

	Parameter	Reference Std.	Test Condition
3-1	Vibration Test	MIL-STD-883 2007 Condition A	10~2000Hz, 1.52mm, 20g, each axis for 4 hrs
		JESD22-B103 Condition 1	
3-2	Thermal Shock	MIL-STD-883 1010 Condition B	-55°C, 125°C; soak time is 10 mins, with total 200 cycles
		JESD22-A104 Condition B	
3-3	Mechanical Shock	MIL-STD-883 2002 Condition B	1500G, half-sine, 0.5ms, each axis for 3 times.
		JESD22-B104 Condition B	



## ■ RECOMMENDED IR REFLOW PROFILE

➤ IR REFLOW PROFILE OF CERAMIC SMD PRODUCTS FOR Pb FREE PROCESS

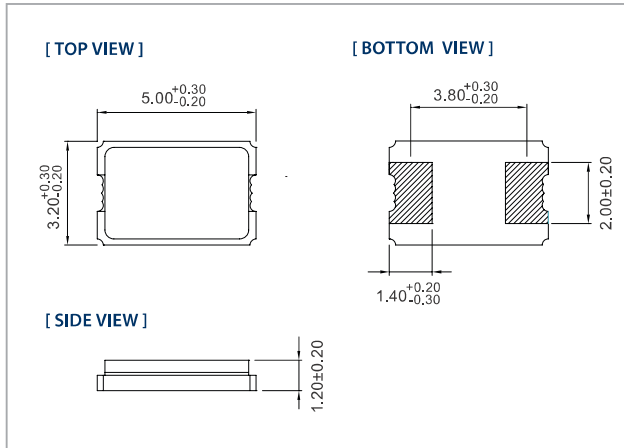




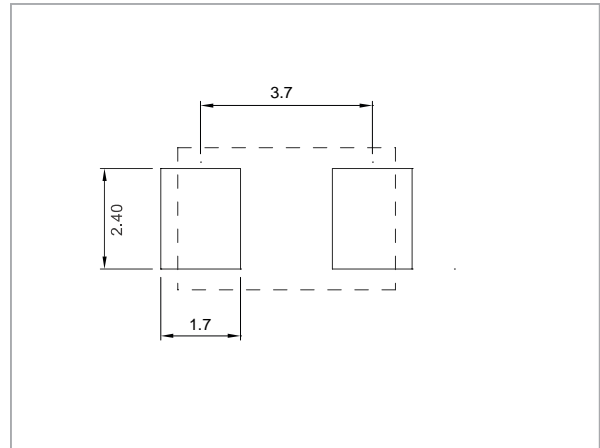
## ■ PRODUCT DIMENSIONS

### ➤ DIMENSIONS

**DIMENSION (mm)**

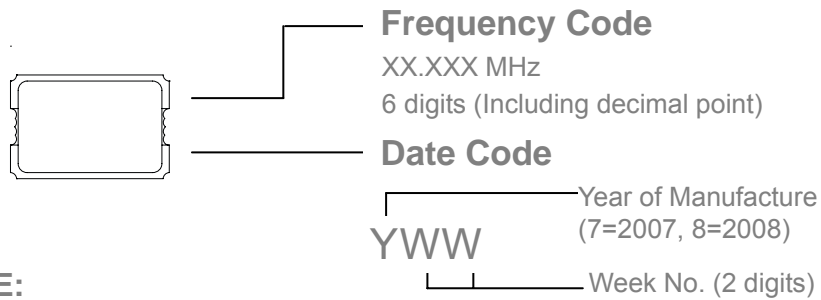


**SOLDER PAD LAYOUT (mm)**

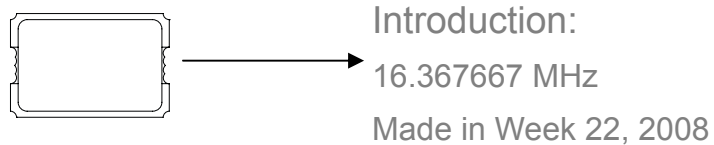


## ■ PRODUCT IDENTIFICATION (MARKING)

### ➤ PROCEDURE: LASER

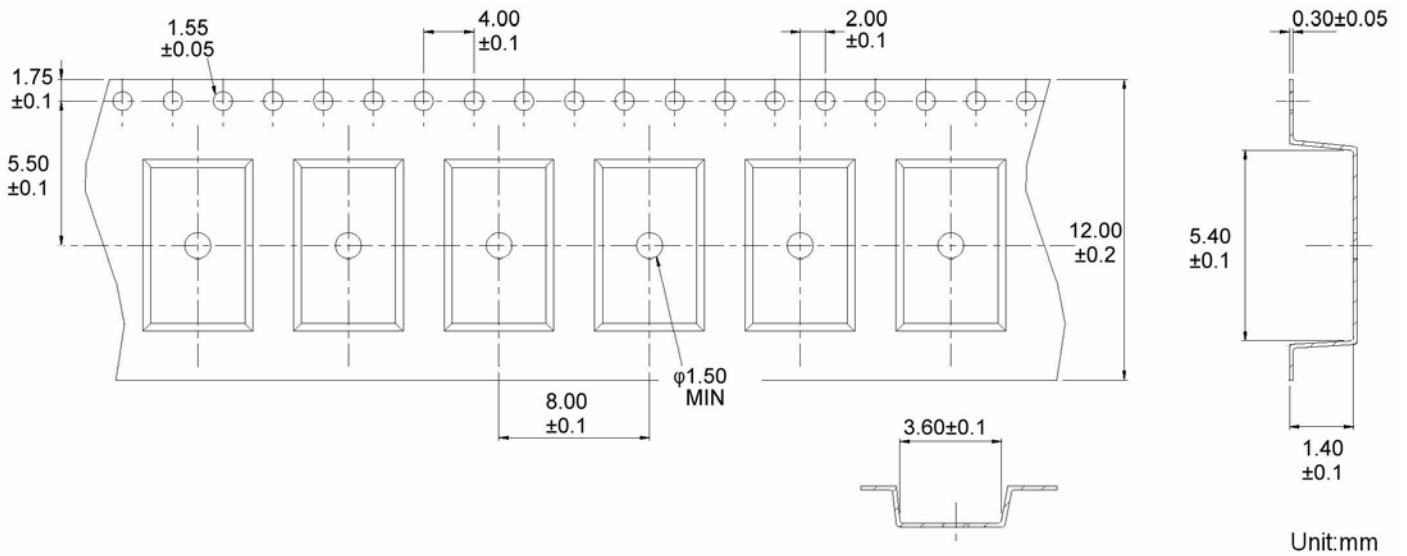


### ➤ FOR EXAMPLE:

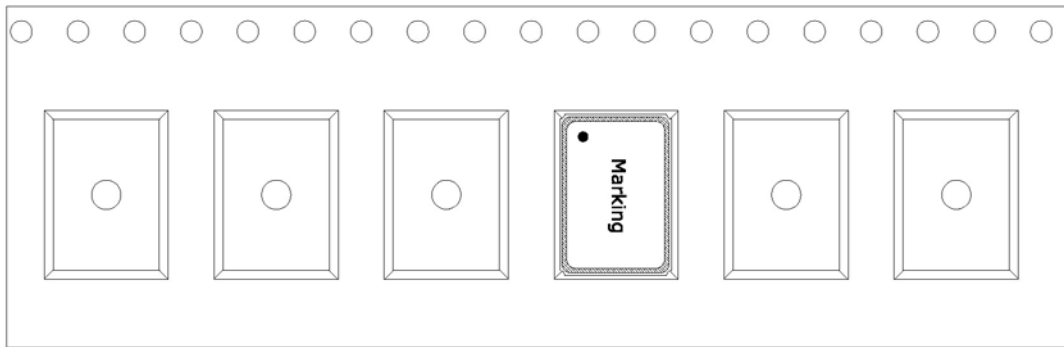


## PACKAGE INFORMATION

### TAPE (CARRIER) DIMENSIONS



### THE DIRECTION OF PACKING



### REEL DIMENSIONS

